

CLAIMS

1. An electronic component comprising predominantly organic functional layers, which has at least one through-plating (3) whose cross-sectional profile (Figures 1 through 8) is so characteristic that it can be seen therefrom that prior to the application of at least one central functional layer (4, 5) at least one lower functional layer (2) was locally treated.

2. An electronic component as set forth in claim 1 wherein the cross-sectional profile shows as the through-plating (3) a free-standing raised portion of electrically conductive or non-conductive material.

3. An electronic component as set forth in claim 2 wherein the conductive material includes polyaniline, pedot, carbon black, graphite, conducting silver and/or metal and/or a mixture thereof.

4. An electronic component as set forth in claim 2 wherein the central functional layer (4, 5) and/or the non-conducting material includes an insulating material such as polyhydroxystyrene, polymethylmethacrylate and/or polystyrene and/or a semiconducting material such as polyalkylthiophene and/or polyfluorene and/or a mixture thereof.

5. An electronic component as set forth in one of the preceding claims wherein the surface of the through-plating (3) in the form of a raised portion has a roughness which promotes later contacting.

6. An electronic component as set forth in one of the preceding claims wherein the cross-sectional profile shows a chemical treatment at least of a lower functional layer (2).

7. An electronic component as set forth in one of the preceding claims wherein the cross-sectional profile shows a physical treatment at least of a lower functional layer (2).

8. An electronic component as set forth in one of the preceding claims wherein the cross-sectional profile shows a local disruption location (7) on the at least one lower functional layer.

9. An electronic component as set forth in one of the preceding claims wherein the cross-sectional profile shows a preceding locally restricted change in the surface energy of the lower functional layer (2), at which no wetting by a subsequently applied organic material of a subsequent central functional layer (4, 5) occurred.

10. An electronic component as set forth in one of the preceding claims wherein a material (7) locally applied to the lower functional layer (2) is removed again prior to or after application of the central functional layer (4,5).

11. An electronic component as set forth in one of the preceding claims wherein the component is made up of a plastic substrate which includes one of the following materials: PET, PP, PEN, polyimide, polyamide and/or coated paper.

12. A process for the production of at least one through-plating of an electronic component comprising predominantly organic material, wherein the through-plating is formed prior to application of the insulating layer.

13. Use of a component as set forth in one of claims 1 through 11 for the production of electronic lowest-cost products such as RFID tags, labels and/or others.